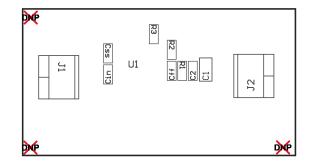
## ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV:	: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 7/23/2	2015 8:58:45	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00597	REV: E1	SVN REV	: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/23/2	2015 8:58:46	PM	TEXAS INSTRUMENTS

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